

SCHOTTKY DIE SPECIFICATION

TYPE: SB520

General Description: 20 V 5 A Standard VF

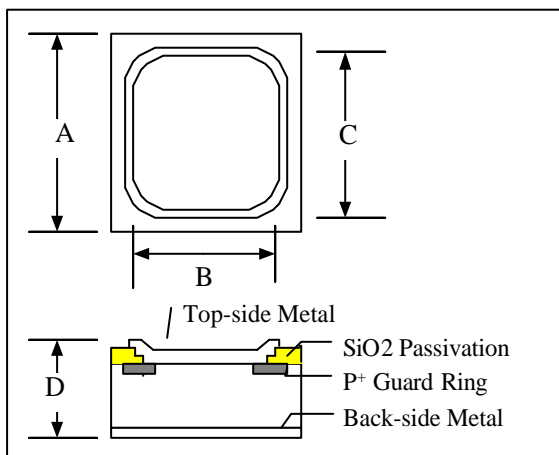
Single Anode

ELECTRICAL CHARACTERISTICS	SYM	Spec. Limit	Die Sort	UNIT
DC Blocking Voltage: Ir=1mA(for wafer form)	VRRM	20	22.5	Volt
Ir=0.5mA (for dice form)				
Average Rectified Forward Current	IFAV	5		Amp
Maximum Instantaneous Forward Voltage				
@ 5 Amperes, Ta=25°C	VF MAX	0.5	0.49	Volt
Maximum Instantaneous Reverse Voltage				
VR= 20 Volt, Ta=25°C	IR MAX	0.3	0.25	mA
Maximum Junction Capacitance @ 0V, 1MHZ	Cj MAX			pF
MAXIMUM RATINGS				
Nonrepetitive Peak Surge Current	IFSM	150		Amp
Operating Junction Temperature	Tj	-65 to 125		°C
Storage Temperatures	TSTG	-65 to 125		°C

Specification apply to die only. Actual performance may degrade when assembled.

MEMT does not guarantee device performance after assembly.

Data sheet information is subjected to change without notice.

DICE OUTLINE DRAWING


DIM	ITEM	um ²	Mil ²
A	Die Size	1838	72.36
B	Top Metal Pad Size	1738	68.4
C	Passivation Seal	1758	69.2
D	Thickness (Min)	254	10
	Thickness (Max)	305	12

PS:

(1)Cutting street width is around 80um(3.14mil).

(2)Both of top-side and back-side metals are Ti/Ni/Ag